



AMENDMENT TRANSMITTAL LETTER			Docket No. 03226/387001; P9280	
Application No. 10/824,455-Conf. #6609	Filing Date April 14, 2004	Examiner D. W. Owens	Art Unit 2811	

Applicant(s): Wen-Chun Zheng et al.

Invention: LIDLESS CHIP PACKAGE EFFECTIVELY HAVING CO-PLANAR FRAME AND SEMICONDUCTOR DIE SURFACES

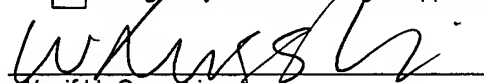
TO THE COMMISSIONER FOR PATENTS

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

CLAIMS AS AMENDED					
	Claims Remaining After Amendment	Highest Number Previously Paid	Number Extra Claims Present	Rate	
Total Claims	20	- 20 =		x	
Independent Claims	3	- 3 =		x	
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					
Other fee (please specify):					
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT:					0.00

- ☒ Large Entity ☐ Small Entity
- ☒ No additional fee is required for this amendment.
- ☐ Please charge Deposit Account No. _____ in the amount of \$ _____.
A duplicate copy of this sheet is enclosed.
- ☐ A check in the amount of \$ _____ to cover the filing fee is enclosed.
- ☐ Payment by credit card. Form PTO-2038 is attached.
- ☒ The Director is hereby authorized to charge and credit Deposit Account No. 50-0591 as described below. A duplicate copy of this sheet is enclosed.
- ☒ Credit any overpayment.
- ☒ Charge any additional filing or application processing fees required under 37 CFR 1.16 and 1.17.


Wasif H. Qureshi
Attorney Reg. No.: 51,048

Dated: March 17, 2005

OSHA & MAY L.L.P.
1221 McKinney St., Suite 2800
Houston, Texas 77010
(713) 228-8600

I hereby certify that this correspondence is being deposited with the U.S. Postal Service as Express Mail, Airbill No. EV562273215US, in an envelope addressed to: MS Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on the date shown below.

Dated: March 17, 2005

Signature:  (Yuki Tsukuda)



3-18-05

IFCw

Docket No.: 03226/387001; P9280
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Wen-Chun Zheng et al.

Confirmation No.: 6609

Application No.: 10/824,455

Art Unit: 2811

Filed: April 14, 2004

Examiner: D. W. Owens

For: LIDLESS CHIP PACKAGE EFFECTIVELY
HAVING CO-PLANAR FRAME AND
SEMICONDUCTOR DIE SURFACES

REPLY UNDER 37 C.F.R. § 1.111

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In response to the Office Action dated January 26, 2005, please reconsider the present application in view of the following.